



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

| | | | |
|--|----------------------------|------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: TIDM-TM4C129USBHS | REV: A0 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: TIDM-TM4C129USBHS | | |
| PLOT NAME = Component SideAssembly Drawing | GENERATED : 9/9/2016 | 3:18:25 PM | TEXAS INSTRUMENTS |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

| | | | |
|---|---------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: TIDM-TM4C129USBHS | REV: A0 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: TIDM-TM4C129USBHS | | |
| PLOT NAME = Solder SideAssembly Drawing | GENERATED : 9/9/2016 3:18:31 PM | TEXAS INSTRUMENTS | |

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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